

YTX-6000 X-Ray

Automated In-line X-Ray Inspection System



- **Highest Defect Detection**
- **Fast Throughput**
- **Quick Set-up**
- **Superior Software**
- **Cost Effective**

YESTech's versatile YTX-6000 conveyorized Inspection System offers SMT and semiconductor packagers complete inspection of critical hidden features and solder joints. The YTX-6000's proven inspection algorithms provide fast and complete inspection of PCB and other assemblies.

Programming the YTX-6000 is fast and intuitive. Operators typically take less than 30 minutes to create a complete inspection program. The YTX-6000 utilizes a standard package library to simplify training and insure program portability across manufacturing lines.

Newly available image processing technology integrates several techniques and inspection algorithms, to provide complete inspection coverage with an extremely low false failure rate.

Remote programming maximizes machine utilization and real-time SPC monitoring provides a valuable yield enhancement solution.

AUTOMATED X-RAY INSPECTION FOR:

- **Component presence and position**
- **Electronic and sealed assemblies**
- **Visible and hidden solder joints**
 - **BGA / Flip Chip**
 - **Leads**
 - **Voids**

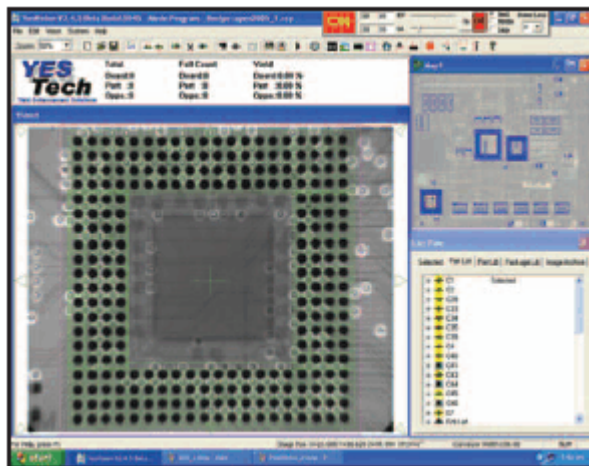
YESTech

"World Leader in Automated Optical Inspections and X-Ray Inspection Systems"

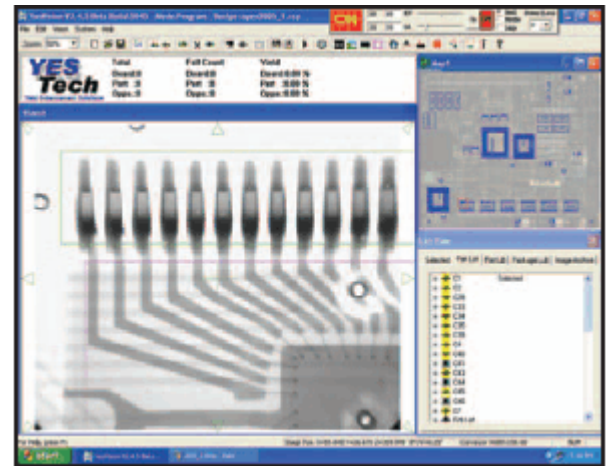
SPECIFICATIONS*

X-Ray Tube	Maintenance free Sealed reflection target 130 Kv, 5 micron spot size 39-watt max. output
Software	CAD Input: Pick and place data, CAD x-y data CAD Translation Package: Excel, Circuitcam, Unicam, CIMBridge, Fabmaster Programming Skill Level: Technician or operator Operating System: Windows XP
Inspection Capabilities	Throughput: 250ms per frame Maximum Board Size: 18" x 20" (450mm x 508mm) Clearance: 2.5" (62mm) top and bottom Minimum Component Size: 0201 Defects Detected: Component: position, missing, wrong, skew, tombstone Lead: bent, lifted, bridging Solder: open, insufficient, short, solder balls BGA: shorts, voids, position, missing ball
Facilities	Power: 110 VAC (220 optional) 50 / 60 Hz 15amps Footprint: 60w" x 68d" x 62h" (1,524mm x 1,727mm x 1,575mm) Weight: 2,500 lbs. (1,136Kg) Machine installation: < 1 hour
Safety	<i>YESTech x-ray systems are manufactured to comply with the federal standard for cabinet x-ray equipment as established in Title 21, Subchapter J of the code of federal regulation sections 1020.40. Lead is used to line the cabinet and door, with lead doped glass for the viewing window. Interlock switches ensure that x-ray radiation can not be generated with any part of the cabinet open or removed.</i>

* Specifications subject to change



Fast, accurate and quick to program, the YTX-6000 inspects for ball presence, size, shape, shorts and voids.



Complete inspection for leads and solder; including toe and heel fillets.



Acrosemi

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